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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/036,389	01/07/2002	Cheng-Yi Liu	2207/12660	3651	
75	590 08/22/2003				
Schwegman, Lundberg, Wocssner & Kluth, P.A.			EXAMINER		
P.O. Box 2938 Minneapolis, MN 55402			TRAN, MAI HUONG C		
willineapolis, w	IN 33402		·		
			ART UNIT	PAPER NUMBER	
			2818		
			DATE MAILED: 08/22/2003	DATE MAILED: 08/22/2003	

Please find below and/or attached an Office communication concerning this application or proceeding.

		_	- lm		
	Application N .	pplicant(s)			
• 3	10/036,389	LIU ET AL.			
Office Action Summary	Examiner	Art Unit			
	Mai-Huong Tran	2818			
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with	th correspondence addre	SS		
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply 1 If NO period for reply is specified above, the maximum statutory period w Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b). Status	36(a). In no event, however, may a reply within the statutory minimum of thirty (3 will apply and will expire SIX (6) MONTH cause the application to become ABAN	y be timely filed 30) days will be considered timely. S from the mailing date of this comm DONED (35 U.S.C. § 133).	unication.		
1) Responsive to communication(s) filed on 21 J	l <u>uly 2003</u> .				
2a) ☐ This action is FINAL . 2b) ☑ Th	is action is non-final.				
3) Since this application is in condition for alloward closed in accordance with the practice under a			nerits is		
Disposition of Claims					
4) Claim(s) 13-27 and 29-44 is/are pending in the					
4a) Of the above claim(s) is/are withdray	vn from consideration.				
5) Claim(s) is/are allowed.	,				
	☑ Claim(s) <u>13-27 and 29-44</u> is/are rejected.				
7) Claim(s) is/are objected to.	Landa a san Paranant	,			
8) Claim(s) are subject to restriction and/or Application Papers	r election requirement.				
9) The specification is objected to by the Examine	r				
10) The drawing(s) filed on is/are: a) accept		Evaminer			
·— ••• · · · · · · · · · · · · · · · · ·					
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a). 11) The proposed drawing correction filed on is: a) approved b) disapproved by the Examiner.					
If approved, corrected drawings are required in reply to this Office action.					
12) The oath or declaration is objected to by the Ex	•				
Priority under 35 U.S.C. §§ 119 and 120					
13) Acknowledgment is made of a claim for foreign	priority under 35 U.S.C. § 1	119(a)-(d) or (f).			
a) ☐ All b) ☐ Some * c) ☐ None of:	. ,	· · · · · · · · · · · · · · · · · · ·			
1.☐ Certified copies of the priority documents	s have been received.				
2. Certified copies of the priority documents		olication No			
Copies of the certified copies of the prior application from the International Bu See the attached detailed Office action for a list	rity documents have been re reau (PCT Rule 17.2(a)).	eceived in this National Sta	age		
14) Acknowledgment is made of a claim for domesti	c priority under 35 U.S.C. §	119(e) (to a provisional ap	plication).		
 a) ☐ The translation of the foreign language pro 15)☐ Acknowledgment is made of a claim for domesting 	* *				
Attachment(s)	•				
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449) Paper No(s)	5) Notice of Info	mmary (PTO-413) Paper No(s). ormal Patent Application (PTO-1			
S. Patent and Trademark Office					

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DETAILED ACTION

Claim Rejections - 35 U.S.C. § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 13-27 and 29-44 are rejected under 35 U. S. C. § 102 (b) as being anticipated by U.S. Patent No. 5,621,615 to Dawson et al.

Regarding to claim 13, Dawson discloses a method of fabricating an integrated circuit package, comprising mounting a thinned semiconductor die 316 on a planar surface of a heat spreader 306 as set forth in col. 3, lines 55-59, col. 6, lines 4-67, and figs. 3B, 4B.

Claim 14 is rejected under the same rationale set forth above to claim 13.

Claim 15 is rejected under the same rationale set forth above to claim 13.

Regarding to claim 16, the method wherein the die has a thickness of no more than $100 \mu m$ (col. 6, lines 61—64).

Claim 17 is rejected under the same rationale set forth above to claim 13.

Claim 18 is rejected under the same rationale set forth above to claim 13.

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Claim 19 is rejected under the same rationale set forth above to claim 13.

Claim 20 is rejected under the same rationale set forth above to claim 13.

Claim 21 is rejected under the same rationale set forth above to claim 13.

Claim 22 is rejected under the same rationale set forth above to claim 13.

Claim 23 is rejected under the same rationale set forth above to claim 13.

Regarding to claim 24, Dawson discloses a method of fabricating an integrated circuit package, comprising providing a planar heat spreader; mounting a plurality of thinned semiconductor dice 316, 318 on to a planar surface of the heat spreader to form a plurality of conjoined microelectronic packages; and singulating the plurality of conjoined microelectronic packages as set forth in col. 6 lines 4-67 and figs. 3B and 4B.

Claim 25 is rejected under the same rationale set forth above to claim 24.

Claim 26 is rejected under the same rationale set forth above to claim 24.

Claim 27 is rejected under the same rationale set forth above to claim 24.

Claim 29 is rejected under the same rationale set forth above to claim 24.

Claim 30 is rejected under the same rationale set forth above to claim 24.

Regarding to claim 31, the method wherein the die has a thickness of no more than 100 µm (col. 6, lines 61—64).

Regarding to claim 32, Dawson discloses a method of fabricating an integrated circuit package, comprising mounting a thinned semiconductor die on a planar surface of

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15. .

a heat spreader, wherein the thinned semiconductor die has a thickness of no more than $100 \mu m$, and wherein mounting includes depositing a metallization layer on a back surface of the die as set forth in col. 3, lines 55-59, col. 6, lines 4-67, and figs. 3B, 4B.

Claim 33 is rejected under the same rationale set forth above to claim 32.

Claim 34 is rejected under the same rationale set forth above to claim 32.

Claim 35 is rejected under the same rationale set forth above to claim 32.

Claim 36 is rejected under the same rationale set forth above to claim 32.

Claim 37 is rejected under the same rationale set forth above to claim 32.

Claim 38 is rejected under the same rationale set forth above to claim 32.

Claim 39 is rejected under the same rationale set forth above to claim 32.

Claim 40 is rejected under the same rationale set forth above to claim 32.

Claim 41 is rejected under the same rationale set forth above to claim 32.

Claim 42 is rejected under the same rationale set forth above to claim 32.

Claim 43 is rejected under the same rationale set forth above to claim 32.

Claim 44 is rejected under the same rationale set forth above to claim 32.

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Conclusion

Any inquiry concerning this communication on earlier communications from the

examiner should be directed to Mai-Huong Tran, (703) 305-1958. The examiner can

normally be reached on Monday-Thursday from 8:00 AM to 6:30 PM. The examiner's

supervisor, David Nelms can be reached on (703) 308-4910.

The fax phone number for the organization where this application or proceeding is

assigned is (703) 872-9318. Any inquiry of a general nature or relating to the status of

this application or proceeding should be directed to the receptionist whose telephone

number is (703) 308-0956.

Mai-Huong Tran

HOAI HO PRIMARY EXAMINER